

# 300mA Low-Dropout Voltage Linear Regulator

## ICR0603N5

### General Description

The ICR0603N5 ultra-low quiescent current regulator series features low dropout voltage and low current in the standby mode. With less than 500nA quiescent current at no load, the ICR0603N5 is ideally suited for standby micro-control-unit systems, especially for always-on applications like portable, and other battery-operated systems. The ICR0603N5 series retains all the features that are common to low dropout regulators including a low dropout PMOS pass device, short circuit protection, and thermal shutdown.

The ICR0603N5 series has a 6V maximum operating voltage limit, a -40 °C to 125 °C operating temperature range, and ±2% output voltage tolerance. The ICR0603N5 series is available in SOT-23-5L package.

### Features

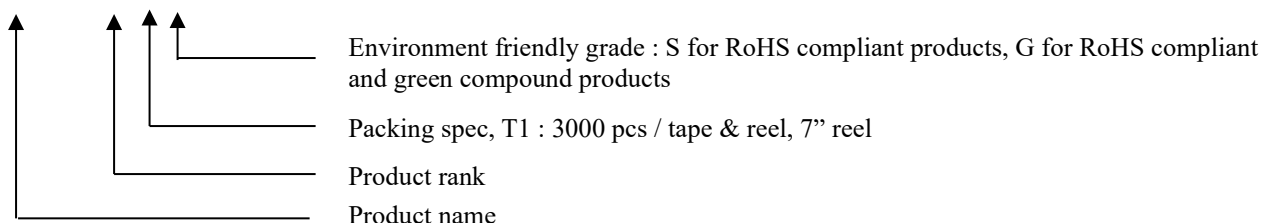
- Output Current of 300mA
- Output Voltage Tolerances of ±2%
- $V_{IN}$  range up to 6V
- Internal Short-Circuit Current Limit
- RoHS compliant, Pb-free package
- Dropout voltage : 400mV@ $I_{OUT}=300mA$
- Ultra Low Quiescent Current :  $I_Q=500nA$  typ.
- Internal Thermal Overload Protection
- Ceramic Capacitor Stable

### Applications

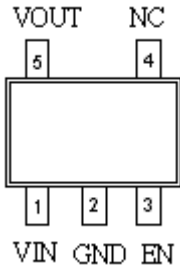
- Portable, Battery powered Equipment
- Ultra Low Power Microcontroller
- Notebook Computers

### Ordering Information

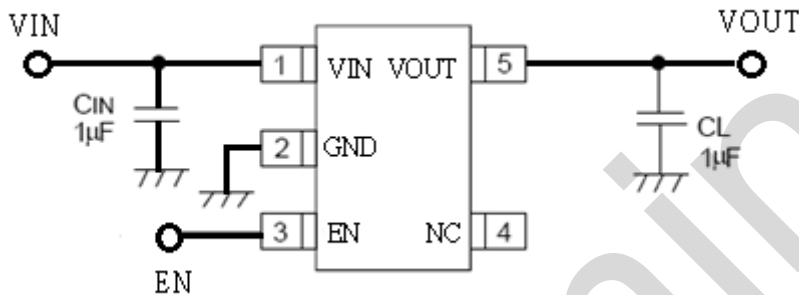
| Part Number      | Output Voltage | Marking | Package                            | Shipping               |
|------------------|----------------|---------|------------------------------------|------------------------|
| ICR0603N5-0-T1-G | 3.3V           | 0603    | SOT-23-5L (RoHS compliant package) | 3000 pcs / Tape & Reel |
| ICR0603N5-A-T1-G | 2.8V           | 603A    |                                    |                        |
| ICR0603N5-B-T1-G | 2.5V           | 603B    |                                    |                        |
| ICR0603N5-C-T1-G | 1.8V           | 603C    |                                    |                        |



## Pin Configuration



## Typical Application Circuit



## Pin Assignment

| Pin Name | Pin No. | Pin Function  |
|----------|---------|---------------|
| VIN      | 1       | Power Input   |
| GND      | 2       | Ground.       |
| EN       | 3       | ON/OFF Enable |
| NC       | 4       | No Connection |
| VOUT     | 5       | Output        |

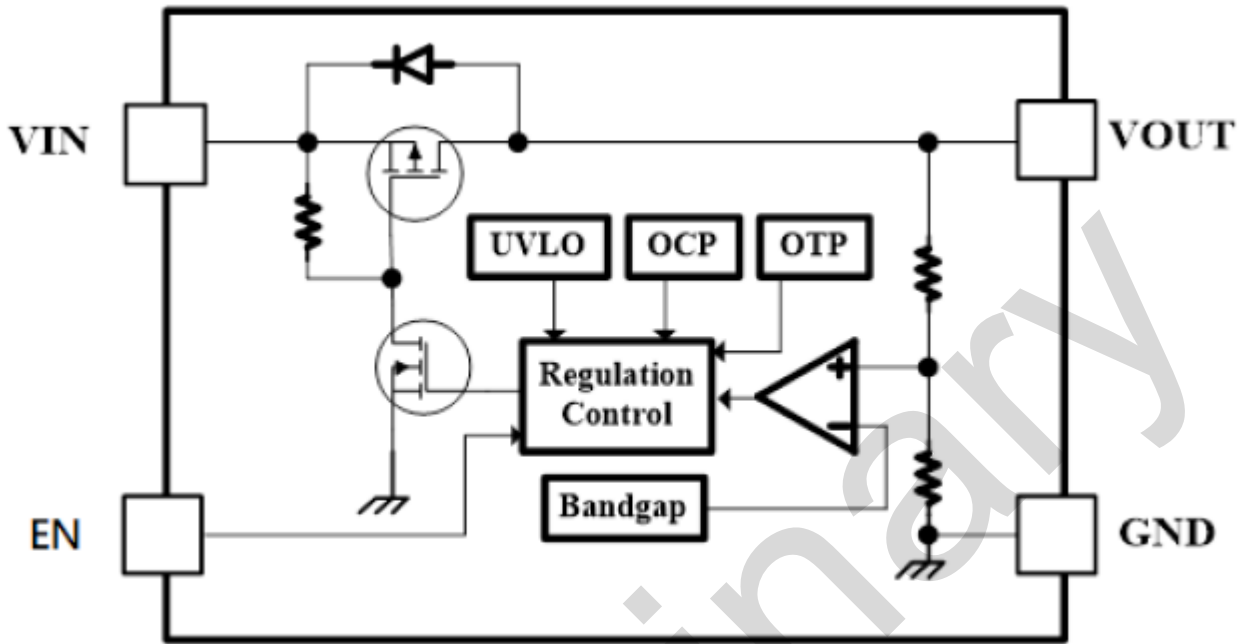
## Absolute Maximum Ratings

| Parameter                           | Symbol           | Ratings   | Units |
|-------------------------------------|------------------|-----------|-------|
| Input Voltage                       | V <sub>IN</sub>  | -0.3~+6.5 | V     |
| Output Current                      | I <sub>OUT</sub> | 300       | mA    |
| Lead Temperature(Soldering, 10 sec) | T <sub>s</sub>   | 300       | °C    |
| Continuous Total Power Dissipation  | P <sub>D</sub>   | 250       | mW    |
| Storage Temperature Range           | T <sub>stg</sub> | -65~+150  | °C    |

## Recommended Operating Condition

| Parameter                  | Symbol          | Ratings   | Units |
|----------------------------|-----------------|-----------|-------|
| Input Voltage              | V <sub>IN</sub> | +2.5~+5.5 | V     |
| Junction Temperature Range | T <sub>j</sub>  | -40~+125  | °C    |

### Function Block Diagram





### Electrical Characteristics

@  $T_J=25^{\circ}\text{C}$ ,  $V_{IN}=V_{EN}=V_{OUT}+1\text{V}$ ,  $I_{OUT}=1\text{mA}$ ,  $C_{IN}=C_{OUT}=1\mu\text{F}$ , unless otherwise specified

| Parameter                   | Symbol            | Test Conditions                                | Min | Typ | Max | Units              |
|-----------------------------|-------------------|--|-----|-----|-----|--------------------|
| Output Voltage Accuracy     | $V_{OUT}$         |  | -2% | -   | 2%  | V                  |
| Line Regulation             | $\Delta V_{Line}$ | $V_{IN}=V_{OUT}+1\text{V}$ to 5.5V             | -   | 0.6 | 1.5 | %                  |
| Load Regulation             | $\Delta V_{Load}$ | $I_{OUT}=1\text{mA}$ to 150mA                  | -   | -   | 1   | %                  |
|                             |                   | $I_{OUT}=1\text{mA}$ to 300mA                  | -   | -   | 3   |                    |
| Dropout Voltage             | $V_{DROP}$        | $I_{OUT}=100\text{mA}$ , $V_{OUT}=3.3\text{V}$ | -   | 130 | -   | mV                 |
|                             |                   | $I_{OUT}=300\text{mA}$ , $V_{OUT}=3.3\text{V}$ | -   | 400 | -   | mV                 |
| Quiescent Current           | $I_Q$             |  | -   | 0.5 | 1   | $\mu\text{A}$      |
| Current Limit               | $I_{CL}$          |  | 360 | 560 |     | mA                 |
| Enable High Level           | $V_{ENHI}$        |  | 0.6 |     |     | V                  |
| Enable Low Level            | $V_{ENLO}$        |  | -   | -   | 0.2 | V                  |
| Thermal Shutdown            | $T_{SD}$          |  | -   | 150 | -   | $^{\circ}\text{C}$ |
| Thermal Shutdown Hysteresis | $T_{SDHY}$        |  | -   | 20  | -   | $^{\circ}\text{C}$ |

**Typical Characteristics**  
 ICR0603N5 (3.3V)

Fig 1. Start Up from EN

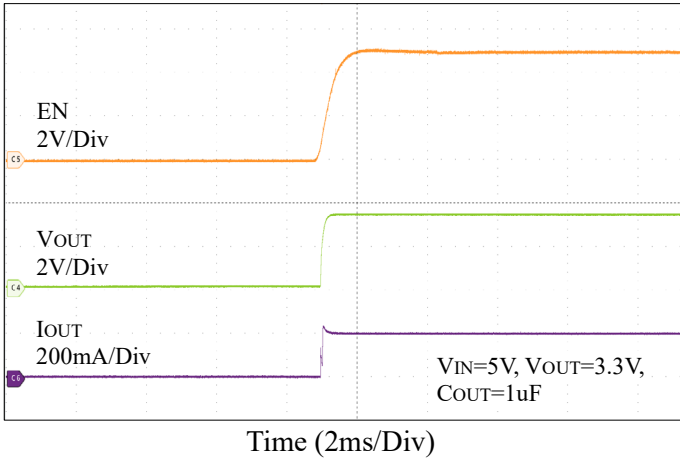


Fig 2. Start Up from VIN

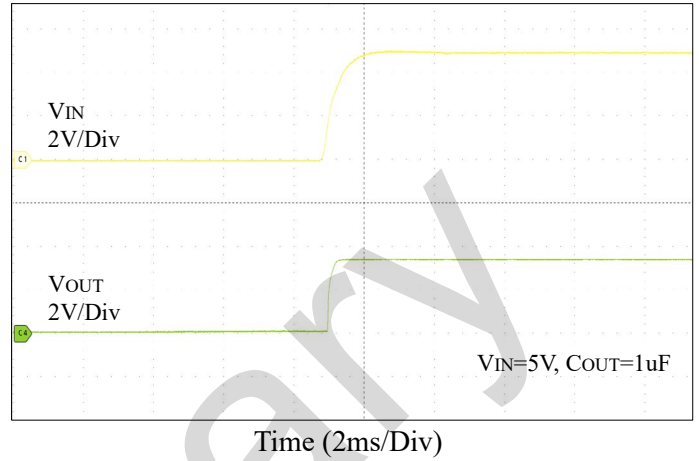


Fig 3. Load Transient

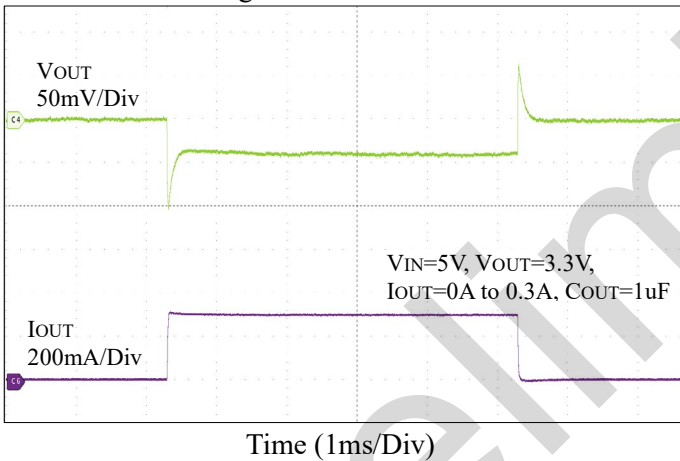


Fig 4. VOUT Short-GND

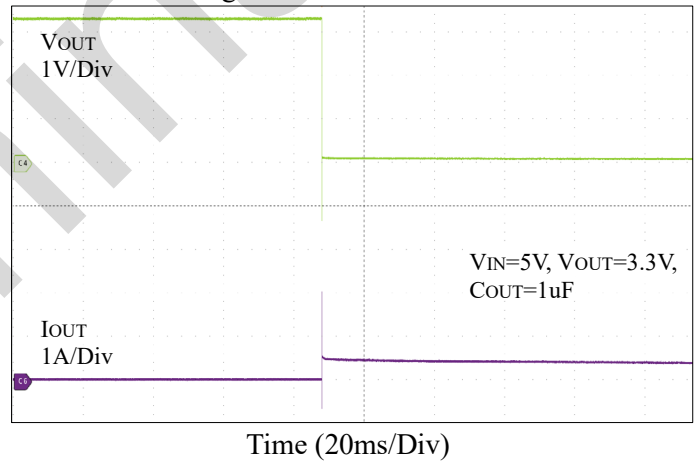


Fig 5. VOUT Short-Release

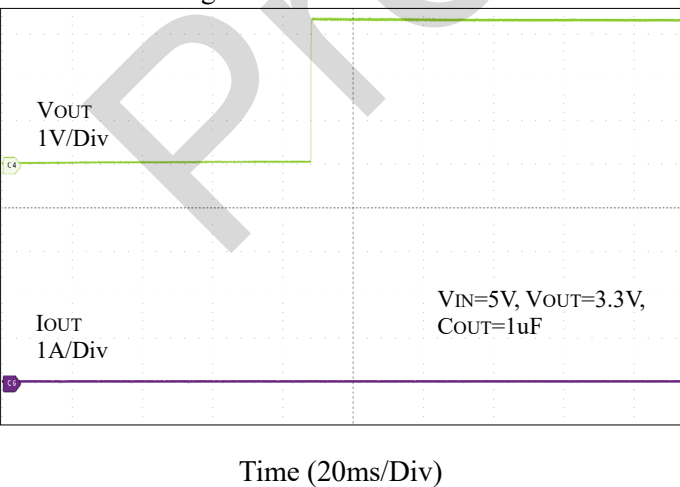
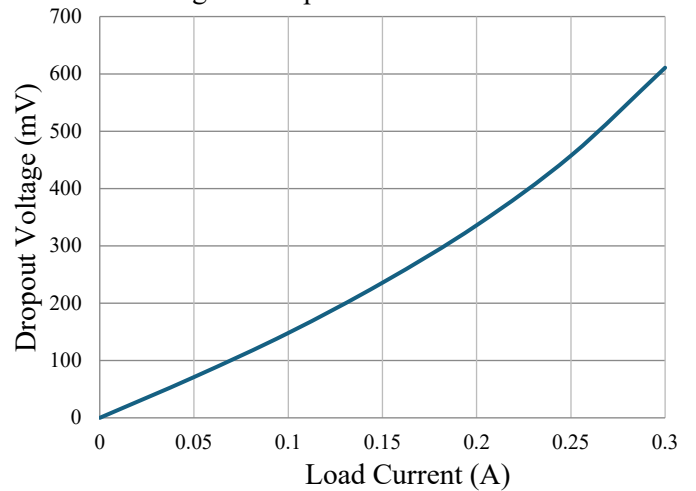
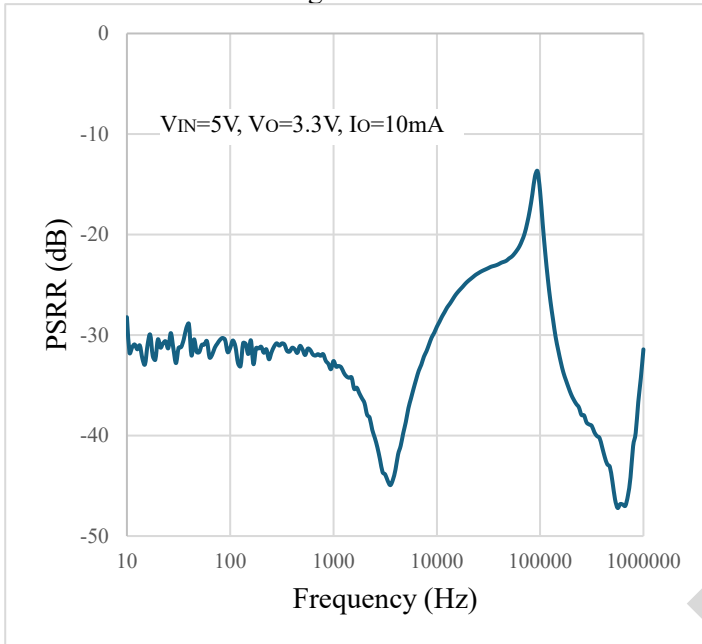


Fig 6. Vdrop vs Load Current

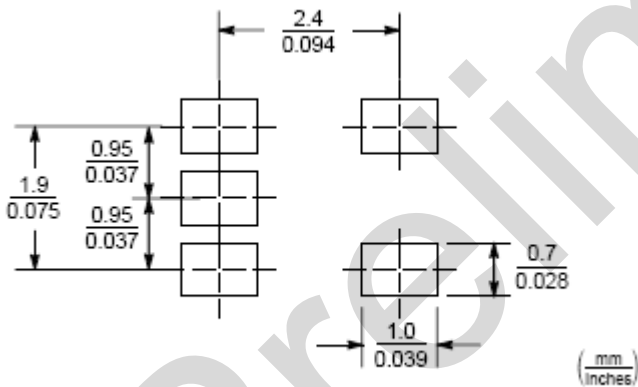


## Typical Characteristics

Fig 7. PSRR



## Recommended Soldering Footprint

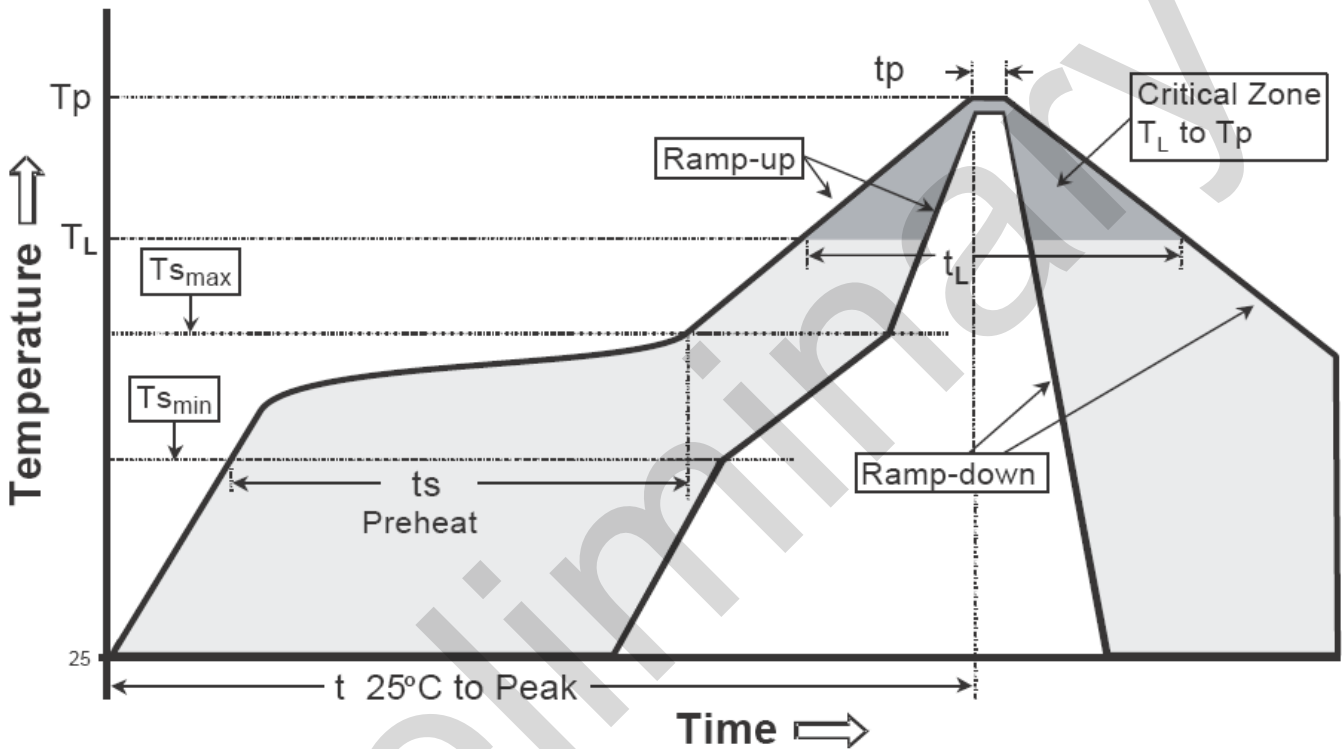




**Recommended wave soldering condition**

|                 |                  |                 |
|-----------------|------------------|-----------------|
| Product         | Peak Temperature | Soldering Time  |
| Pb-free devices | 260 +0/-5 °C     | 5 +1/-1 seconds |

**Recommended temperature profile for IR reflow**

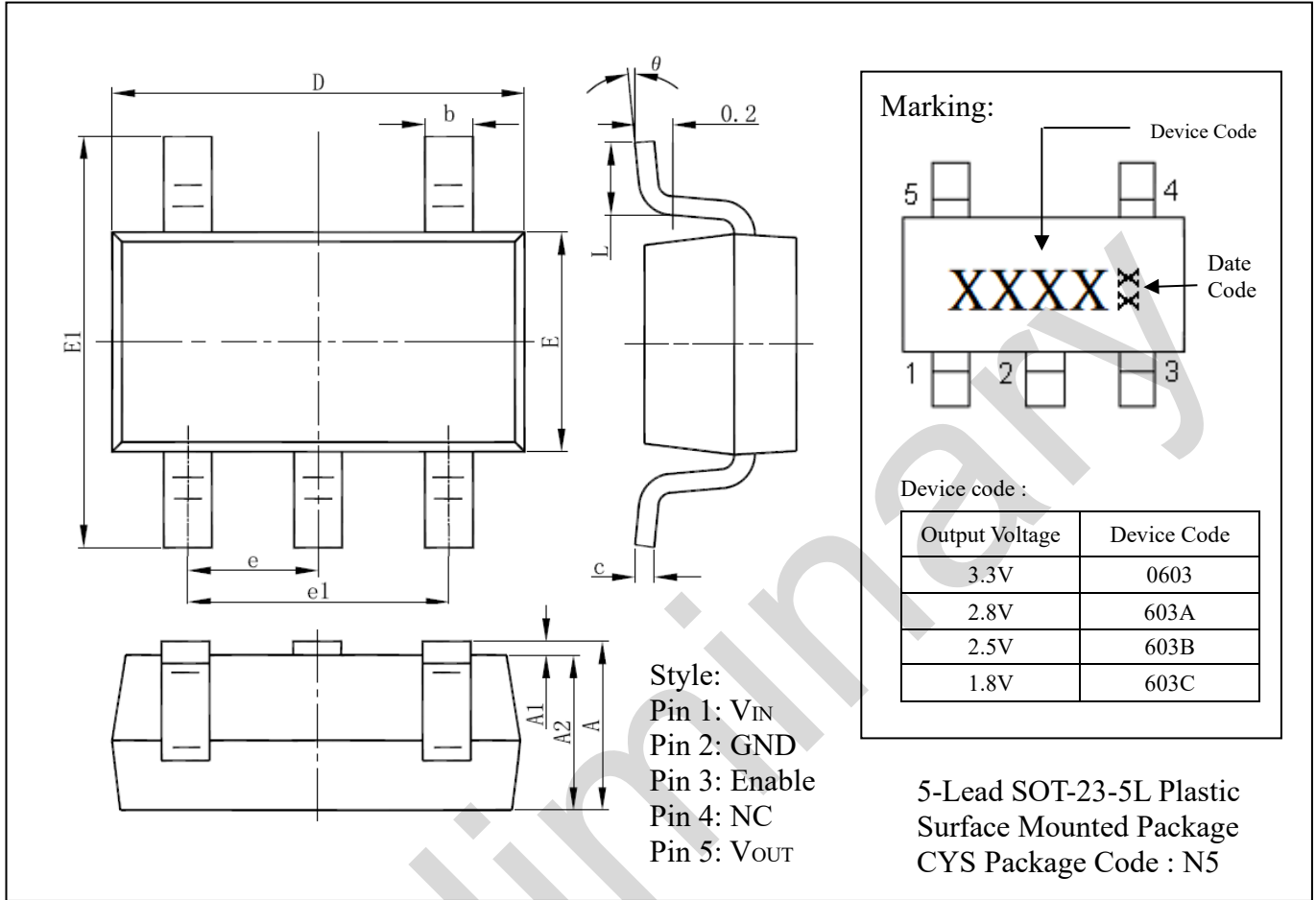


| Profile feature                                | Sn-Pb eutectic Assembly | Pb-free Assembly |
|--|-------------------------|------------------|
| Average ramp-up rate (Tsmax to Tp)             | 3°C/second max.         | 3°C/second max.  |
| Preheat  |                         |                  |
| -Temperature Min(Ts min)                       | 100°C                   | 150°C            |
| -Temperature Max(Ts max)                       | 150°C                   | 200°C            |
| -Time(ts min to ts max)                        | 60-120 seconds          | 60-180 seconds   |
| Time maintained above:                         |                         |                  |
| -Temperature (T <sub>L</sub> )                 | 183°C                   | 217°C            |
| - Time (t <sub>L</sub> )                       | 60-150 seconds          | 60-150 seconds   |
| Peak Temperature(T <sub>P</sub> )              | 240 +0/-5 °C            | 260 +0/-5 °C     |
| Time within 5°C of actual peak temperature(tp) | 10-30 seconds           | 20-40 seconds    |
| Ramp down rate                                 | 6°C/second max.         | 6°C/second max.  |
| Time 25 °C to peak temperature                 | 6 minutes max.          | 8 minutes max.   |

Note : All temperatures refer to topside of the package, measured on the package body surface.



**SOT-23-5L Dimension**



| DIM | Millimeters |       | Inches |       | DIM | Millimeters |       | Inches |       |
|-----|-------------|-------|--------|-------|-----|-------------|-------|--------|-------|
|     | Min.        | Max.  | Min.   | Max.  |     | Min.        | Max.  | Min.   | Max.  |
| A   | 1.050       | 1.250 | 0.041  | 0.049 | E   | 1.500       | 1.700 | 0.059  | 0.067 |
| A1  | 0.000       | 0.100 | 0.000  | 0.004 | E1  | 2.650       | 2.950 | 0.104  | 0.116 |
| A2  | 1.050       | 1.150 | 0.041  | 0.045 | e   | 0.950       | (BSC) | 0.037  | (BSC) |
| b   | 0.300       | 0.500 | 0.012  | 0.020 | e1  | 1.800       | 2.000 | 0.071  | 0.079 |
| c   | 0.100       | 0.200 | 0.004  | 0.008 | L   | 0.300       | 0.600 | 0.012  | 0.024 |
| D   | 2.820       | 3.020 | 0.111  | 0.119 | θ   | 0°          | 8°    | 0°     | 8°    |

Notes : 1.Controlling dimension : millimeters.  
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

**Material :**

- Lead :Pure tin plated.
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0.

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